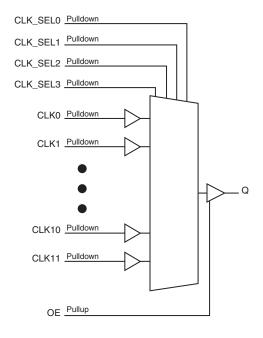
## **General Description**

The 850S1201 is a low skew12:1 Single-ended Clock Multiplexer. The 850S1201 has 12 selectable single-ended clock inputs and 1 single- ended clock output. The device operates up to 250MHz and is packaged in a 20 TSSOP package.

### **Features**

- 12:1 single-ended multiplexer
- Nominal output impedance: 20Ω (V<sub>DD</sub> = 3.3V)
- Maximum output frequency: 250MHz
- Propagation delay: 2.7ns (maximum)
- Full 3.3V or 2.5V supply modes
- -40°C to 85°C ambient operating temperature
- Available in lead-free (RoHS 6) package

# **Block Diagram**



# **Pin Assignment**

01.10	_	-00	H 01 1/7
CLK8□	1	20	CLK7
CLK9 □	2	19	□CLK6
CLK10 □	3	18	CLK5
CLK11 ☐	4	17	□CLK4
V <sub>DD</sub> □	5	16	□CLK3
CLK_SEL0 □	6	15	CLK2
CLK_SEL1 ☐	7	14	□CLK1
CLK_SEL2 ☐	8	13	□CLK0
CLK_SEL3 □	9	12	□GND
OE	10	11	□Q

850S1201

20-Lead TSSOP 6.50mm x 4.40mm x 0.925mm package body G Package Top View



# **Pin Description and Pin Characteristics**

**Table 1. Pin Descriptions** 

Number	Name	1	Гуре	Description
1	CLK8	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
2	CLK9	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
3	CLK10	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
4	CLK11	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
5	V <sub>DD</sub>	Power		Power supply pin.
6, 7. 8, 9	CLK_SEL0, CLK_SEL1, CLK_SEL2, CLK_SEL3	Input	Pulldown	Clock select inputs. See Table 3. LVCMOS / LVTTL interface levels.
10	OE	Input	Pullup	Output enable pin for Q output. LVCMOS/LVTTL interface levels.
11	Q	Output		Single-ended clock output. LVCMOS/LVTTL interface levels.
12	GND	Power		Power supply ground.
13	CLK0	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
14	CLK1	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
15	CLK2	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
16	CLK3	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
17	CLK4	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
18	CLK5	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
19	CLK6	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
20	CLK7	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**Table 2. Pin Characteristics** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			2		pF
C	Power Dissipation Capacitance	V <sub>DD</sub> = 3.465V		10		pF
C <sub>PD</sub>		V <sub>DD</sub> = 2.625V		8		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ
C	Output Impedance	$V_{DD} = 3.3V \pm 5\%$		20		Ω
R <sub>OUT</sub>		V <sub>DD</sub> = 2.5V±5%		25		Ω



# **Function Tables**

**Table 3. Clock Input Function Table** 

	Inputs				
CLK_SEL3	CLK_SEL2	CLK_SEL1	CLK_SEL0	Input Selected to Q	
0	0	0	0	CLK0	
0	0	0	1	CLK1	
0	0	1	0	CLK2	
0	0	1	1	CLK3	
0	1	0	0	CLK4	
0	1	0	1	CLK5	
0	1	1	0	CLK6	
0	1	1	1	CLK7	
1	0	0	0	CLK8	
1	0	0	1	CLK9	
1	0	1	0	CLK10	
1	0	1	1	CLK11	
1	1	0	0	Output goes LOW	
1	1	0	1	Output goes LOW	
1	1	1	0	Output goes LOW	
1	1	1	1	Output goes LOW	



## **Absolute Maximum Ratings**

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V <sub>DD</sub>	4.6V
Inputs, V <sub>I</sub>	-0.5V to V <sub>DD</sub> + 0.5V
Outputs, V <sub>O</sub>	-0.5V to V <sub>DD</sub> + 0.5V
Package Thermal Impedance, $\theta_{JA}$	87.2°C/W (0 mps)
Storage Temperature, T <sub>STG</sub>	-65°C to 150°C

## **DC Electrical Characteristics**

## Table 4A. Power Supply DC Characteristics, $V_{DD}$ = 3.3V ± 5%, $T_A$ = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Positive Supply Voltage		3.135	3.3	3.465	V
I <sub>DD</sub>	Power Supply Current	Output Unterminated			49	mA

## Table 4B. Power Supply DC Characteristics, $V_{DD}$ = 2.5V ± 5%, $T_A$ = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Positive Supply Voltage		2.375	2.5	2.625	V
I <sub>DD</sub>	Power Supply Current	Output Unterminated			41	mA



Table 4C. LVCMOS/LVTTL DC Characteristics,  $V_{DD}$  = 3.3V ± 5% or 2.5V ± 5%,  $T_A$  = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V	Input		V <sub>DD</sub> = 3.465V	2		V <sub>DD</sub> + 0.3	V
V <sub>IH</sub>	High Voltage		V <sub>DD</sub> = 2.625V	1.7		V <sub>DD</sub> + 0.3	V
V	Input		V <sub>DD</sub> = 3.465V	-0.3		0.8	V
$V_{IL}$	Low Voltage		V <sub>DD</sub> = 2.625V	-0.3		0.7	V
I <sub>IH</sub>	Input	CLK[0:11], CLK_SEL[0:3]	V <sub>DD</sub> = V <sub>IN</sub> = 3.465V or 2.625V			150	μА
	High Current OE	OE	V <sub>DD</sub> = V <sub>IN</sub> = 3.465V or 2.625V			10	μΑ
I <sub>IL</sub>	Input	CLK[0:11], CLK_SEL[0:3]	V <sub>DD</sub> = 3.465V or 2.625V, V <sub>IN</sub> = 0V	-10			μΑ
	Low Current OE		V <sub>DD</sub> = 3.465V or 2.625V, V <sub>IN</sub> = 0V	-150			μΑ
V.	Output High Voltage; NOTE 1		$V_{DD} = 3.3V \pm 5\%, I_{OH} = -12mA$	2.6			V
V <sub>OH</sub>			$V_{DD} = 2.5V \pm 5\%, I_{OH} = -12mA$	1.8			V
V <sub>OL</sub>	Output Low Voltage; NOTE 1		$V_{DD} = 3.3V \pm 5\% \text{ or } 2.5V \pm 5\%,$ $I_{OL} = 12\text{mA}$			0.5	V

NOTE 1: Output terminated with  $50\Omega$  to  $V_{DD}/2$ . See Parameter Measurement Information section. Load Test Circuit diagrams.

## **AC Electrical Characteristics**

Table 5A. AC Characteristics,  $V_{DD}$  = 3.3V ± 5%,  $T_A$  = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency				250	MHz
tp <sub>LH</sub>	Propagation Delay, Low-to-High; NOTE 1		1.4		2.7	ns
<i>t</i> jit	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section	155.52MHz, Integration Range: 12kHz – 20MHz		0.35		ps
tsk(i)	Input Skew				175	ps
tsk(pp)	Part-to-Part Skew; NOTE 2, 3				600	ps
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Time	20% to 80%	100		500	ps
odc	Output Duty Cycle; NOTE 4	$f \leq 200 MHz$	46		54	%
ouc	Output Duty Cycle, NOTE 4	f = 250MHz	40		60	%
MUX <sub>ISOLATION</sub>	MUX Isolation	155.52MHz		43		dB

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DD}/2$  of the output.

NOTE 2: Defined as skew between outputs on different devices operating at the same supply voltage and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 3: This parameter is defined according with JEDEC Standard 65.

NOTE 4: Input duty cycle must be 50%.



Table 5B. AC Characteristics,  $V_{DD}$  = 2.5V ± 5%,  $T_A$  = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency				250	MHz
tp <sub>LH</sub>	Propagation Delay, Low-to-High; NOTE 1		1.5		2.7	ns
<i>t</i> jit	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section	155.52MHz, Integration Range: 12kHz – 20MHz		0.32		ps
tsk(i)	Input Skew				195	ps
tsk(pp)	Part-to-Part Skew; NOTE 2, 3				600	ps
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Time	20% to 80%	80		600	ps
odo	Output Duty Cycle: NOTE 4	$f \leq 200MHz$	46		54	%
odc	Output Duty Cycle; NOTE 4	f = 250MHz	40		60	%
MUX <sub>ISOLATION</sub>	MUX Isolation	155.52MHz		43		dB

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1: Measured from  $V_{DD}\!/\!2$  of the input to  $V_{DD}\!/\!2$  of the output.

NOTE 2: Defined as skew between outputs on different devices operating at the same supply voltage and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 3: This parameter is defined according with JEDEC Standard 65.

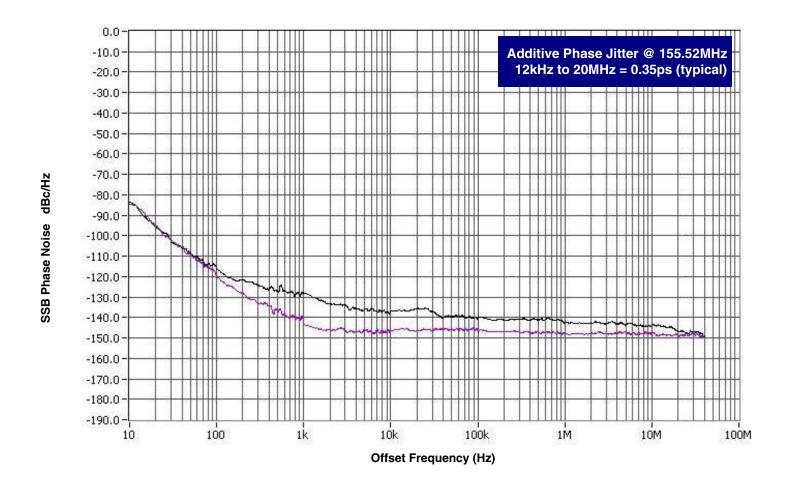
NOTE 4: Input duty cycle must be 50%.



### **Additive Phase Jitter**

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio

of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.

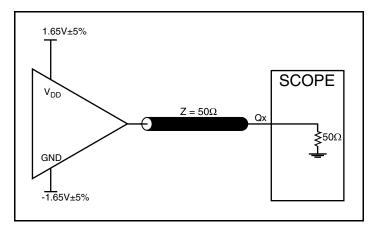


As with most timing specifications, phase noise measurements has issues relating to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This

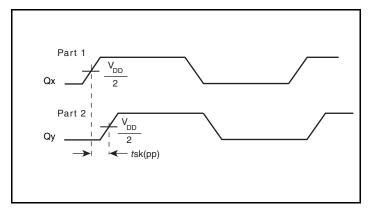
is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependent on the input source and measurement equipment.



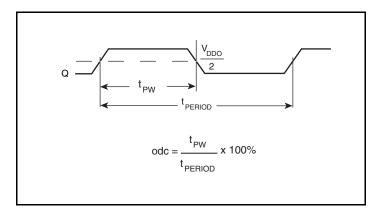
## **Parameter Measurement Information**



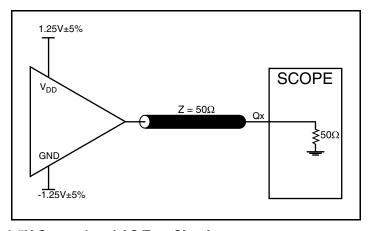
3.3V Output Load AC Test Circuit



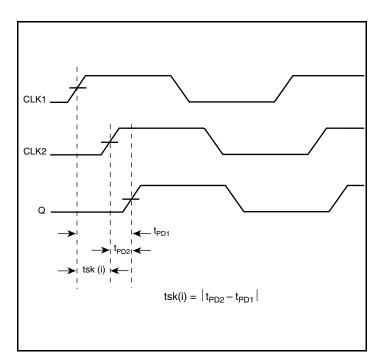
Part-to-Part Skew



**Output Duty Cycle/Pulse Width/Period** 



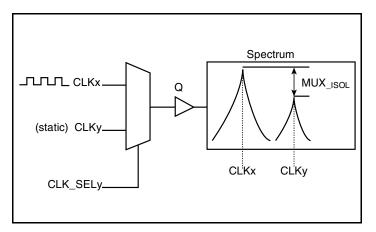
2.5V Output Load AC Test Circuit

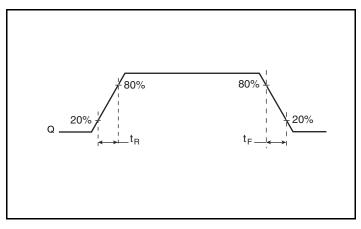


**Input Skew** 



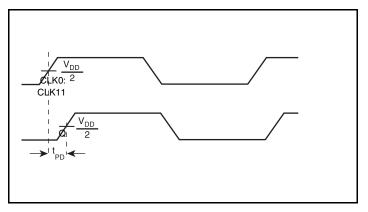
## **Parameter Measurement Information, continued**





**MUX** Isolation

**Output Rise/Fall Time** 



**Propagation Delay** 

## **Recommendations for Unused Input Pins**

## Inputs:

#### **CLK Inputs**

For applications not requiring the use of a clock input, it can be left floating. Though not required, but for additional protection, a  $1k\Omega$  resistor can be tied from the CLK input to ground.

#### **LVCMOS Control Pins**

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A  $1 \mathrm{k}\Omega$  resistor can be used.



# **Reliability Information**

Table 6.  $\theta_{\text{JA}}$  vs. Air Flow Table for a 20 Lead TSSOP

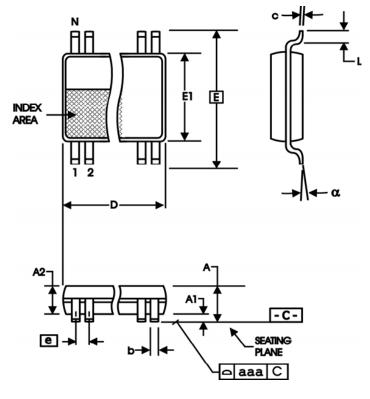
$\theta_{JA}$ vs. Air Flow				
Meters per Second	0	1	2.5	
Multi-Layer PCB, JEDEC Standard Test Boards	87.2°C/W	82.9	80.7	

#### **Transistor Count**

The transistor count for 850S1201 is: 649

# **Package Outline and Package Dimensions**

Package Outline - G Suffix for 20 Lead TSSOP



**Table 7. Package Dimensions** 

All Dimensions in Millimeters					
Symbol	Minimum	Maximum			
N	2	20			
Α		1.20			
<b>A</b> 1	0.05	0.15			
A2	0.80	1.05			
b	0.19	0.30			
С	0.09	0.20			
D	6.40	6.60			
Е	6.40	Basic			
E1	4.30	4.50			
е	0.65	Basic			
L	0.45	0.75			
α	0°	8°			
aaa		0.10			

Reference Document: JEDEC Publication 95, MO-153



# **Ordering Information**

## **Table 8. Ordering Information**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
850S1201BGILF	ICS0S1201BIL	"Lead-Free" 20 Lead TSSOP	Tube	-40°C to 85°C
850S1201BGILFT	ICS0S1201BIL	"Lead-Free" 20 Lead TSSOP	Tape & Reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.



# **Revision History Sheet**

Rev	Table	Page	Description of Change	Date
	T5A, T5B	5, 6	AC Characteristics Table - added thermal note.	
Α	Т8	11	Ordering Information Table - correct Part/Order Number from 850S1201AGILF/T to 850S1201BGILF/T.	1/4/10
В		1	General Description - deleted HiperClocks logo.  Throughout the datasheet - deleted "ICS" prefix and "I" suffix from the part number.  Updated header/footer.	2/8/16



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